



CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as first class mail in an envelope addressed to:

**Box: Non-Fee Amendment
Commissioner for Patents
Washington, D.C. 20231**

on 04.30.03


Gloria Simmons

In re application of: Shi, et al.

Group No.: 2812

Serial Number: 09/648,777

Examiner: Nguyen, Ha T.

Filing Date: August 28, 2000

TECHNOLOGY CENTER 2800
MAY - 7 2003

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Title: Process and Material for Low-Cost Flip-Chip Solder Interconnect Structures

Attached are the following documents for filing with the USPTO:

Postcard
Amendment Transmittal Form (1 Page)
First Response (with Amendments)

In re PATENT application of: Shi, et al.

Serial No: 09/648,777

Filed: August 28, 2000

Examiner: Nguyen, Ha T.

Group No.: 2812

Docket No.: 820701-1080

Title: Process and Material for Low-Cost Flip-Chip Solder Interconnect Structures

AMENDMENT TRANSMITTAL LETTER

Box: Non-Fee Amendment

Commissioner of Patents

Washington, D.C. 20231

Sir:

Transmitted herewith is an amendment in the above-identified application.

Response/Amendment

Fee as Calculated Below

No additional fee is required.

Small Entity status has been established.

Terminal Disclaimer

Corrected Drawings

Other:

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CLAIMS AS AMENDED FOR LARGE ENTITY					
	Claims After Amendment	Highest Prev. Paid For	Extra	Rate	Additional Fee
Total Claims	53	- 53	0	x \$18.00	= \$0.00
Independent Claims	3	- 3	0	x \$84.00	= \$0.00
Total Additional Fee for this Amendment					= \$0.00

A check in the amount of \$ is enclosed.

A Credit Card Payment Form PTO-2038 is attached in the amount of \$

The Commissioner is hereby authorized to charge to our Deposit Account No. the amount of \$ for the fee identified above. A duplicate of this Amendment Transmittal Letter is included herewith.

The Commissioner is authorized to charge any insufficiencies, and the Commissioner is hereby requested to credit any overpayments to our Deposit Account No. 20-0778.

Customer No.: 24504

THOMAS, KAYDEN, HORSTEMEYER
& RISDEY, L.L.P.

Todd Deveau
Todd Deveau, Reg. No. 29,526
Attorney for Applicant(s)

Date: April 30, 2003

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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:

Shi *et al.*

Serial No.: 09/648,777

Filed: August 28, 2000

For: **Process and Material for Low-Cost
Flip-Chip Solder Interconnect Structures**



Group Art Unit: 2812

Examiner: Nguyen, Hiep

Docket No. 820701-1080

TECHNOLOGY CENTER 2800

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FIRST RESPONSE (WITH AMENDMENTS)

Commissioner for Patents
Washington, D.C. 20231

Sir:

The Office Action mailed January 31, 2003 (Paper No. 8) has been received and carefully considered. In response thereto, please enter the following amendments and consider the following remarks.

AUTHORIZATION TO DEBIT ACCOUNT

It is not believed that extensions of time or fees for net addition of claims are required, beyond those which may otherwise be provided for in documents accompanying this paper. However, in the event that additional extensions of time are necessary to allow consideration of this paper, such extensions are hereby petitioned under 37 C.F.R. § 1.136(a), and any fees required therefor (including fees for net addition of claims) are hereby authorized to be charged to deposit account no. 20-0778.